FOR IMMEDIATE RELEASE

Plasma-Therm Expands its Product Portfolio with Acquisition of KOBUS

ST. PETERSBURG, Florida (April 4, 2018) — Plasma-Therm today announced that it has acquired KOBUS, an innovative plasma deposition company, which enables F.A.S.T®, a valuable alternative to ALD where thick and conformal films are required.

This unique deposition method is at the crossroads of ALD and CVD: F.A.S.T. stands for “Fast Atomic Sequential Technology.” F.A.S.T. is enabled by proprietary CVD reactor design combined with pulsing capability, and while capable of depositing in traditional ALD mode, it is optimal for thick and conformal layer deposition and offers new solutions for 3D integration challenges.

KOBUS offers a unique portfolio of equipment for both mature and advanced materials deposition, which merges well with Plasma-Therm’s operation, expanding the plasma-based deposition and etch suite of products for all silicon and compound semiconductor emerging applications.

This acquisition will allow Plasma-Therm to establish a solid base in Europe and conduct R&D development in the Grenoble “Silicon Valley,” a region fueled with R&D, startups and large semiconductor corporations.

About Plasma-Therm
Plasma-Therm LLC is a manufacturer of leading plasma etch, deposition, and advanced packaging equipment for specialty semiconductor and nanotechnology markets. Plasma-Therm’s plasma-processing and advanced-packaging solutions are used in research, pilot manufacturing, and volume production of wireless, photonics, solid state lighting, MEMS/NEMS, data storage and other devices. Learn more at http://www.plasmatherm.com

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